

DET 2016

The 9th International Conference
on Digital Enterprise Technology

ANNOUNCEMENT AND CALL FOR PAPERS

Intelligent Manufacturing in the Knowledge Economy Era

March 29 - 31, 2016, Nanjing, China



ORGANIZERS

Nanjing University of Aeronautics and Astronautics

State Key Laboratory of Digital Manufacturing Equipment and Technology of China

Aston University

University of Bath

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INTRODUCTION

Digital Enterprise Technology (DET) is “the collection of systems and methods for the digital modelling, simulation and optimization of the collaborative product development, factory and manufacturing processes planning, along their lifecycle”.

The main aim of DET 2016 is to provide an international forum for the exchange of leading edge scientific knowledge and industrial experiences, regarding the development, integration and applications of the various aspects of Digital Enterprise Technologies, in the global manufacturing of the knowledge economy era.

The guiding idea of the conference is to find a common understanding of employing Digital Enterprise Technologies in the factories of the future, moving from automated, to flexible, digital, sustainable, smart and intelligent manufacturing.

SCOPE AND TOPICS

The CIRP sponsored DET 2016 conference focuses on the employment of modern Information and Communication Technologies (ICT) for the modelling, simulation, optimization, control, monitoring, and visualisation of products, factories and manufacturing processes, covering all lifecycle issues across the entire supply chain, starting with product design and development, engineering of factories, machines, equipment and technical processes, commissioning and ramp-up, followed by manufacturing operations, maintenance, factory overhaul and facility management, up to products recycling/re-use, and environmentally friendly

dismantling. Potential delegates are invited to submit papers in or related to the following topics:

Conference website: <http://det2016.nuaa.edu.cn> and <http://www.detconference.org/>

• Product Design and Development:

Product Design, Modelling and Visualisation, Collaborative Engineering, Distributed Design, Cost Engineering, Design for X, Knowledge Based Engineering and CAD/CAM/CAE.

• Manufacturing Technologies and Operations:

Manufacturing Process Modelling and Simulation, Manufacturing Planning and Decision Making, Intelligent CNC Machining, Feature-based Manufacturing, Rapid Manufacturing, Inspection and Measurement, Assembly Planning and Simulation.

• Factory and Production Systems:

Virtual Factory, Digital Factory, Cyber-Physical Systems, Smart Factory, Factory Automation and Control, Man-Machine Interaction, Human-Robot Interaction, Production System Design, Reconfiguration and Optimisation.

• IT Systems & Interoperability:

Systems Communication and Interoperability, IT-based Product-Service Systems, Service oriented and Cloud-based environments, Knowledge Management frameworks, Big Data and Data Mining, Social Media Technologies in Design and Manufacturing.



• Life Cycle Issues:

Product, Process and Factory Life Cycle Management, Sustainability, Lean Design and Manufacturing, Supply Chain Management, Reverse Engineering, Product-Service Systems, Product Maintenance, Re-manufacturing and Disposal, and Global Manufacturing Issues.

INDUSTRY WORKSHOP

A special Industrial Workshop will be arranged during the Conference to hear the voice of industry, particularly the Chinese manufacturing companies by interdisciplinary dialogues between industry, technology providers and academia.

BEST PAPER AWARDS AND SPECIAL JOURNAL ISSUES

All accepted papers will be published in CIRP Procedia (EI). Best papers will be awarded in each of the above-mentioned conference topics by international assessment panels. There are opportunities for selected papers to be published as special issues of the Proceedings of the Institution of Mechanical Engineers Part B-Journal of Engineering Manufacture (SCI) and the International Journal of Advanced Manufacturing Technology (SCI).

IMPORTANT DATES

Full Paper Submission:	15 January 2016
Notification of Paper Acceptance:	15 February 2016
Final Manuscript:	28 February 2016

HOW TO SUBMIT

All submissions are to be made on-line via the EasyChair conference system:

<https://easychair.org/conferences/?conf=det2016>

For more information, visit the DET2016 website:

<http://det2016.nuaa.edu.cn> and <http://www.detconference.org/>

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Yvonne Ascott, University of Bath, UK

KEY INDUSTRIAL PARTICIPANTS:

AVIC Chengdu Aircraft Industrial (Group) Co., Ltd.
AVIC Hongdu Aviation Industry (Group) Co., Ltd.
CASC Shanghai Spaceflight Manufacture (Group) Co., Ltd.
Siemens PLM Software

DMG MORI Co., Ltd.

Artis Marposs

Fastems Ltd.

These industrial participants will give keynote presentations and form the industrial roundtable to discuss industrial requirements, state of the art, and academic research.

REGISTRATION COSTS

Full Author Registration: £400, RMB 4000

Research Student Registration: £300, RMB 3000

Inclusive of paper processing and publishing costs (Abstracts Booklet and PROCEEDIA CIRP publication), refreshments and the Conference Banquet.

CONFERENCE LANGUAGE AND CONTACT

The conference language is English.

Contact E-mail: committee@detconference.org